

Corporate Website TRADE NEWS Posting

February 17, 2020

ELECTRONICS

MacDermid Alpha to Exhibit and Present at the Upcoming IMAPS Device Packaging Conference

(Waterbury, CT USA) - February 17, 2020 – MacDermid Alpha Electronics Solutions, a global leader in high performance semiconductor chemistries and assembly materials, will exhibit total process solutions for emerging packaging at the IMAPS Conference, Fountain Hills, AZ, March 3-5, 2020.

MacDermid Alpha will highlight their entire portfolio of technologies from their MacDermid Enthone, Alpha, Kester, and Compugraphics brands essential to advanced semiconductor packaging and the markets it enables, such as 5G, mobile, smart automotive, high-performance computing, augmented and virtual reality, and artificial intelligence (AI). Showcased will be the recently released STAYDRY Z20 film, a unique getter which employs an active desiccant for water absorption dispersed in a flexible silicone polymer matrix. Also promoted will be the soon-to-be-released Systek UVF 100; a 2-in1 RDL via filling technology for IC substrates.

Dr. Kesheng Feng, Research Director for Metallization, will be presenting *Embedded Trace and RDL Copper Plating Process for Panel Level Packaging Applications*, on Tuesday, March 3 at 3:00pm. The presentation will discuss how MacDermid Alpha is helping advanced packaging suppliers address challenges in fine line copper plating for panel level packaging designs.

MacDermid Alpha's team of industry experts from their Circuitry and Semiconductor divisions will be available at booth #33/34 to discuss the challenges the semiconductor manufacturing sector faces as technology continues to push the limits of performance and miniaturization.

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